



**LEVEL II**

CM-88-88-107

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**C-MU Voter Chip**

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**March 10, 1980**

**DEPARTMENT  
of  
COMPUTER SCIENCE**



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### Abstract

A CMOS LSI chip developed by Carnegie-Mellon University (Pittsburgh, Pa.) in cooperation with Sandia Laboratories (Albuquerque, N.M.) for implementation of bus-level voters is described. Special features based on experience with C.vmp, a SSI/MSI TTL prototype system, are presented and explained. This document provides all information necessary to design triplicated microcomputer systems using this chip as the basis of the voter circuit.

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## Description of the Chip

One standard approach used to achieve fault tolerance has been triplication with voting. The development of low-cost large scale integration, with one-board (or even one-chip) processors, has encouraged applying triplication at the processor-memory bus level. The C.vmp project at Carnegie-Mellon University tested this concept with a system built around triplicated LSI-11 processors [Siew77, Siew78a, Siew78b, Siew78c]. The experience gained in designing and refining a SSI/MSI implemented voter circuit led to the current LSI chip design.

The voter chip contains best two-out-of-three voters for four bus signals: two bidirectional (data) and two unidirectional (control). Figure 1 is a block diagram of the unidirectional voter and Figure 2 is a block diagram of the bidirectional voter. All four voters have a common multiplexing scheme which allows flexibility in controlling the actual voting patterns either statically or dynamically. In addition, the two types of voters have separate mechanisms for synchronization.

Two sets of multiplexors control the voting process itself. The first selects among the voted (best two-out-of-three) result and the three separate signals, allowing nontriplicated devices on any of the buses to "broadcast" their signals. The second set of multiplexors selects separately for each bus whether to use the voted/broadcast signal or the unmodified signal, allowing operation as three independent computers. The table below shows the effect of the multiplexor control signals on the outputs of the voter chip.

<u>IND</u>	<u>BX</u>	<u>BY</u>	<u>Output Signal</u>
0	0	0	Broadcast from bus A
0	0	1	Broadcast from bus B
0	1	0	Broadcast from bus C
0	1	1	Voted result from all three buses
1	-	-	Same as input signal

In addition to the common multiplexing control, the two unidirectional voters also have provision for timing control. Two distinct synchronization issues are addressed. The first is that of synchronous reception of a voted bus control signal by the three processors. A latch controlled by the chip signal G is placed on the voted signal line after the broadcast/vote multiplexor and before the voting/independent multiplexor. Thus, if the processors (or other bus level devices) sample the bus control signal on the edge of a (common) clock, synchronous reception of the signal can be assured by latching it for a suitable interval each clock period.

The second synchronization issue is raised by the nature of the bus protocol. The design implemented assumes a "level signaling convention" such as is used by the LSI-11 bus in relation to the data lines. By this is meant that certain bus control signals, by being at either a high or low level,

indicate the validity of the bus data signals. This is illustrated in Figure 3. A delay after the best two-out-of-three voter is desirable in order to obtain the best results whenever the timings of the three separate devices are not identical. A delay allows a slow module to still provide valid data for voting, and also to stay in step overall with the rest of the system. However, the delay would unnecessarily degrade performance if the three devices have nearly identical timing. To allow for this, the delay circuit must be bypassed whenever all three bus control signals are in agreement.

The implementation of a delay circuit in C.vmp using MSI components consisted of a D flip-flop and a one-shot, as shown in Figure 4. For the LSI implementation, a short shift register which can be either set or cleared asynchronously in all bit positions was used. Two levels of control over the delay desired are provided: clock rate and number of clock periods. The first is simply the frequency of the input clock (CLK), which can range from DC to 0.5 MHz (2.0 MHz at  $V_{DD} = +10v$ ). The second is implemented by a 4:1 multiplexor which chooses the maximum number of clock periods to wait before passing the (delayed) voted signal. Note that only the rising edge of the voted signal is delayed -- the falling edge propagates immediately. The available delays are shown in the table below.

<u>DX</u>	<u>DY</u>	<u>Maximum Delay</u>
0	0	No delay
0	1	Delay up to 2 clock periods
1	0	Delay up to 3 clock periods
1	1	Delay up to 4 clock periods

The special circuit added to the bidirectional voters for purposes of synchronization is a set of latches on the input signals from the processors. The three separate buses have separate latch control signals: GA, GB, and GC. In each case, the corresponding signals are latched when the latch control signal is low, and are passed directly through when the control signal is high. This is useful for data signals which are strobed by the leading edge of a bus control signal and removed shortly thereafter without waiting for any handshaking. This sort of scheme is used by the LSI-11, where the SYNC signal strobes the bus address lines at the start of each bus cycle.

The other special circuit needed in the bidirectional voters is the set of multiplexors which choose the direction of data flow through the voter. The chip control signal DIR selects either the external -- memory and I/O -- bus signals (if low) or the processor bus signals (if high) as input to the actual best two-out-of-three voter.

The flexibility offered by this chip comes largely from the amount of multiplexing performed onchip. Two base modes of operation, voting and independent, are offered to allow tradeoffs between higher reliability with fault masking and higher performance with distributed processing. In addition, nontriplicated devices may be employed even in voting mode, allowing such things as terminals to be

selectively redundant, possibly with fault recovery at the software level. Latches are provided to capture and hold critical bus signals, and a variable delay is provided for synchronization purposes in unidirectional voters. This delay can be varied both by changing the basic clock rate of the delay shift register and by changing the selection control inputs to the following multiplexor. In addition, there is no requirement for signals through different chips to use the same clock frequency or multiplexor setting. All of this adds up to a great deal of freedom for the designer.

### Summary of Voter Chip Signals

#### Power

Pin Number	Pin Name	Description
1	V <sub>DD</sub>	CMOS power: +5v to +10v (higher voltage results in higher speed)
47	V <sub>CC</sub>	TTL power: +5v
25	GND	Reference ground

**Control**

Pin Number	Pin Name	Description
9	IND	Selects between voting mode and independent mode 0 - Voting mode (0 = GND; 1 = High, depending on $V_{DD}$ ) 1 - Independent mode
37	DIR	Selects the direction of data flow for bidirectional voters 0 - From external (memory) to processor 1 - From processor to external (processor)
35,36	BX,BY	Selects broadcast or voting mode 00 - Broadcast from bus A 01 - Broadcast from bus B 10 - Broadcast from bus C 11 - Voted signal from all three buses
12	G	Latch control for unidirectional voters 0 - Latch voted signal 1 - Pass voted signal
26	GA	Latch control for bidirectional voters on bus A 0 - Latch (bidirectional) signals from processor A 1 - Pass (bidirectional) signals from processor A
26	GB	Latch control for bidirectional voters on bus B 0 - Latch (bidirectional) signals from processor B 1 - Pass (bidirectional) signals from processor B
26	GC	Latch control for bidirectional voters on bus C 0 - Latch (bidirectional) signals from processor C 1 - Pass (bidirectional) signals from processor C
43	CLK	Timing clock waveform for unidirectional voter delays
38,39	DX,DY	Select delay for unidirectional voters 00 - No delay 01 - Delay 1-2 clock periods 10 - Delay 2-3 clock periods 11 - Delay 3-4 clock periods

**Data Paths**

Pin Number	Pin Name	Description
13	WPA	Unidirectional signal W from bus A
14	WPB	Unidirectional signal W from bus B
15	WPC	Unidirectional signal W from bus C
6	WVA	Voted unidirectional signal W to bus A
5	WVB	Voted unidirectional signal W to bus B
4	WVC	Voted unidirectional signal W to bus C
16	XPA	Unidirectional signal X from bus A
17	XPB	Unidirectional signal X from bus B
18	XPC	Unidirectional signal X from bus C
3	XVA	Voted unidirectional signal X to bus A
2	XVB	Voted unidirectional signal X to bus B
48	XVC	Voted unidirectional signal X to bus C
19	YPA	Bidirectional signal Y from processor bus A
21	YPB	Bidirectional signal Y from processor bus B
23	YPC	Bidirectional signal Y from processor bus C
20	YEA	Bidirectional signal Y from external (memory) bus A
22	YEB	Bidirectional signal Y from external (memory) bus B
24	YEC	Bidirectional signal Y from external (memory) bus C
46	YVA	Voted bidirectional signal Y to bus A
45	YVB	Voted bidirectional signal Y to bus B
44	YVC	Voted bidirectional signal Y to bus C
27	ZPA	Bidirectional signal Z from processor bus A
41	ZPB	Bidirectional signal Z from processor bus B
31	ZPC	Bidirectional signal Z from processor bus C
42	ZEA	Bidirectional signal Z from external (memory) bus A
40	ZEB	Bidirectional signal Z from external (memory) bus B
32	ZEC	Bidirectional signal Z from external (memory) bus C
28	ZVA	Voted bidirectional signal Z to bus A
29	ZVB	Voted bidirectional signal Z to bus B
30	ZVC	Voted bidirectional signal Z to bus C

## Acknowledgements

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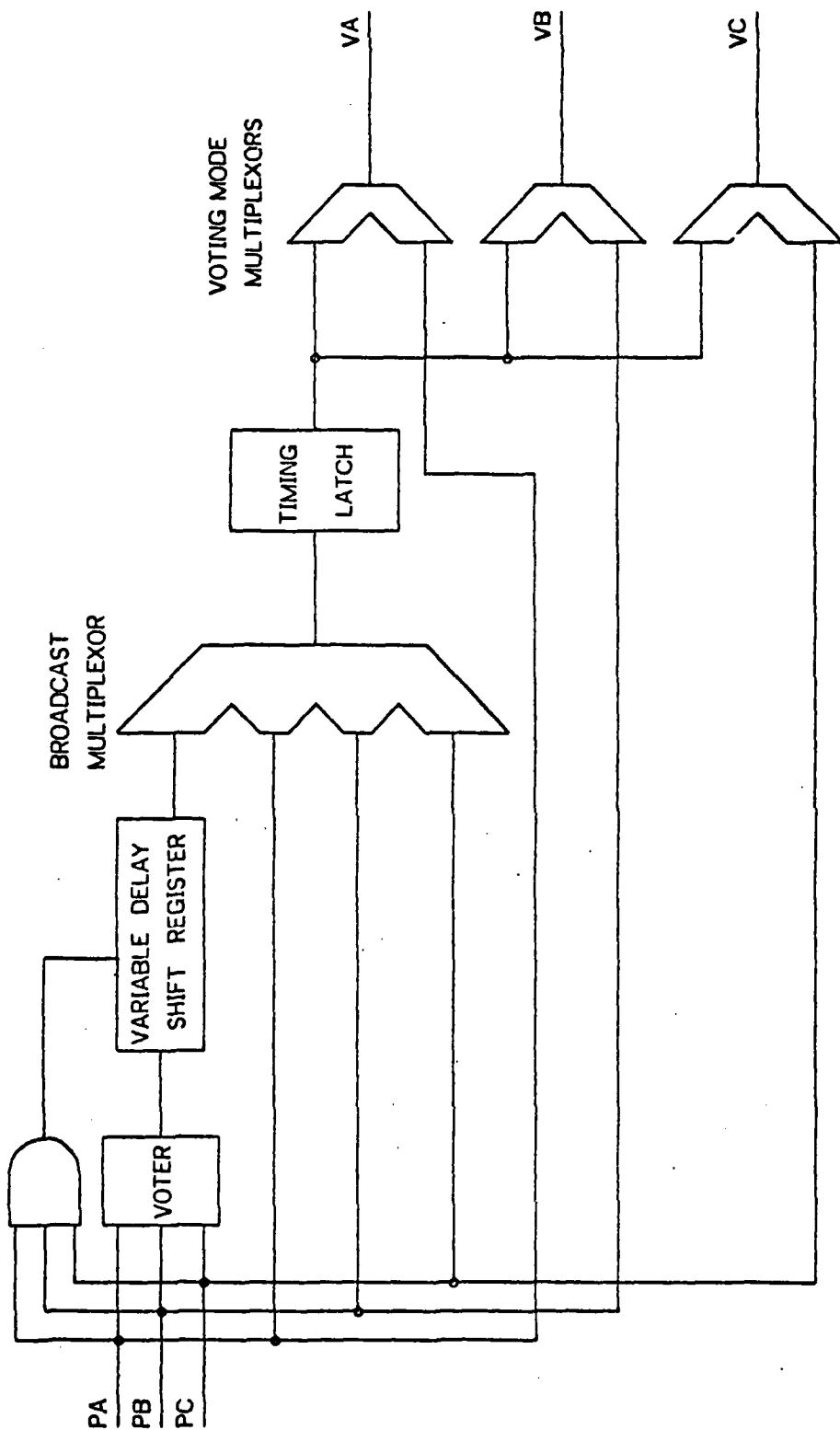


FIGURE 1. UNIDIRECTIONAL VOTER CIRCUIT

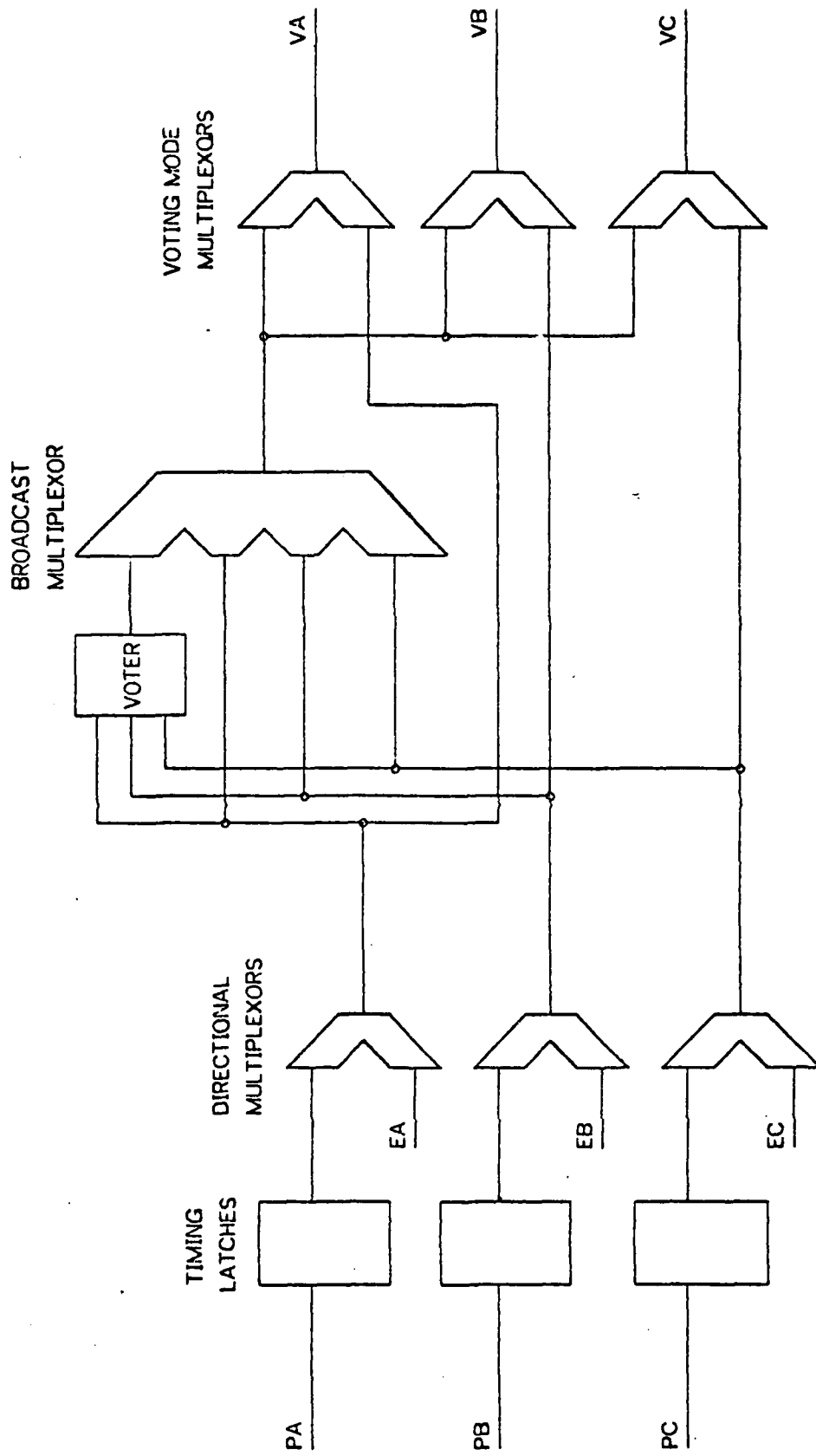


FIGURE 2. BIDIRECTIONAL VOTER CIRCUIT

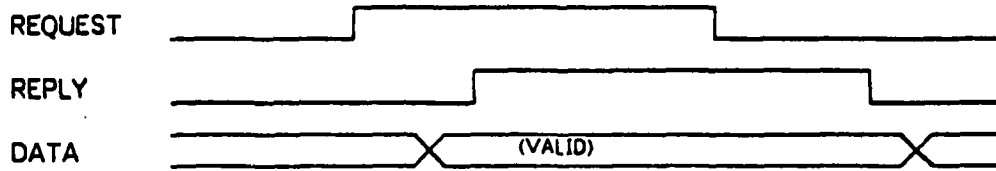


FIGURE 3. LEVEL SIGNALING CONVENTION

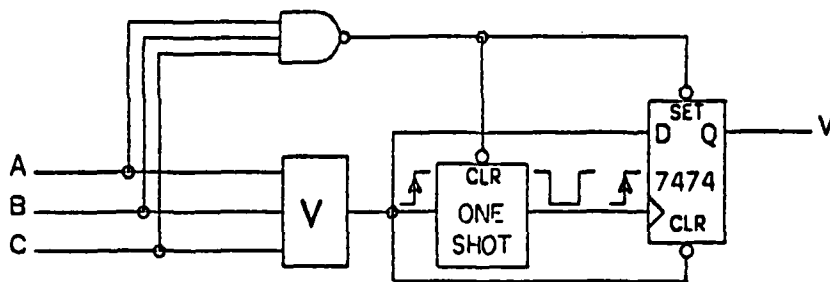


FIGURE 4A. SYNCHRONIZING VOTER

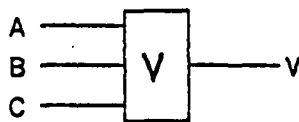
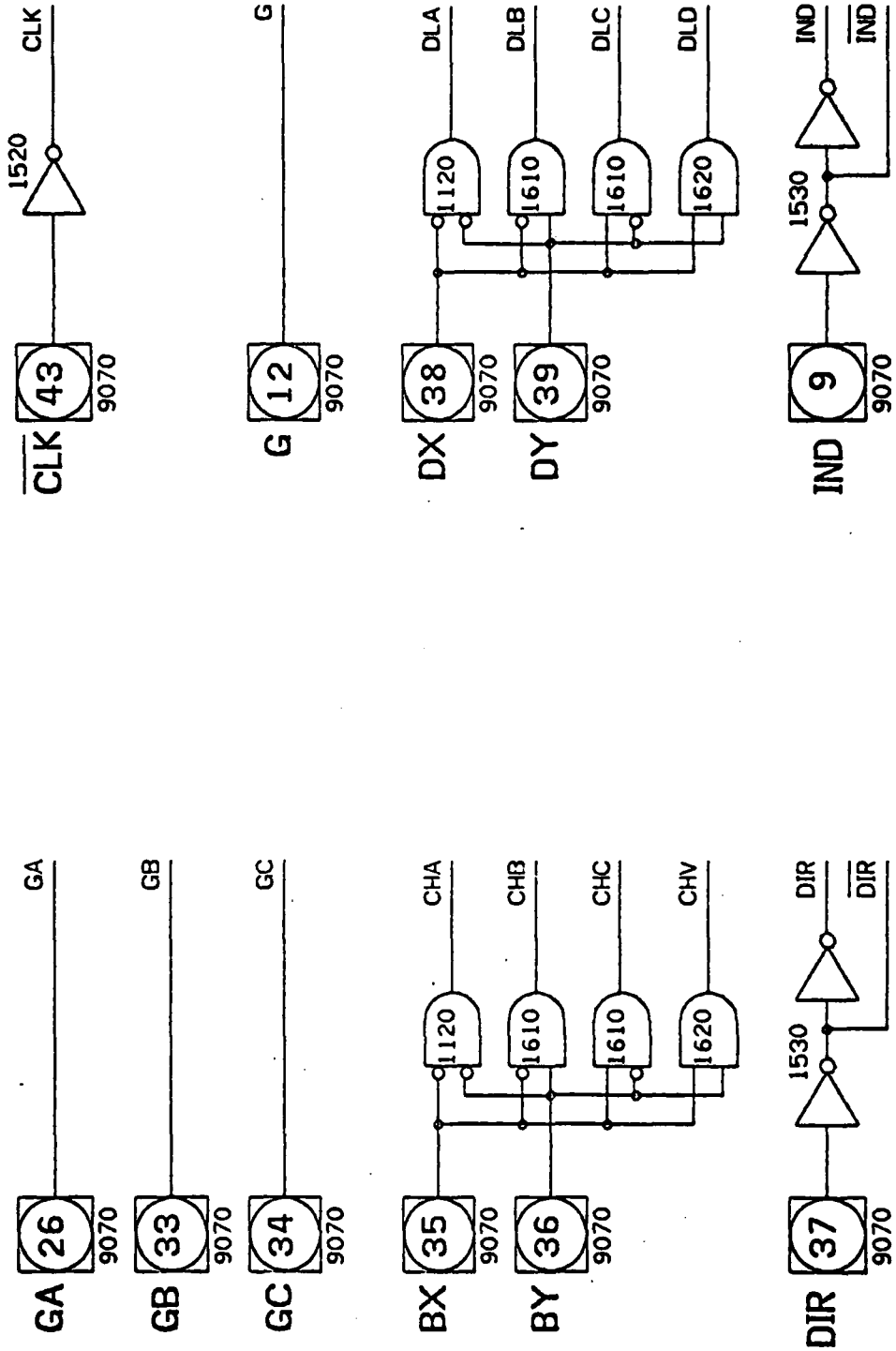


FIGURE 4B. DATA VOTER

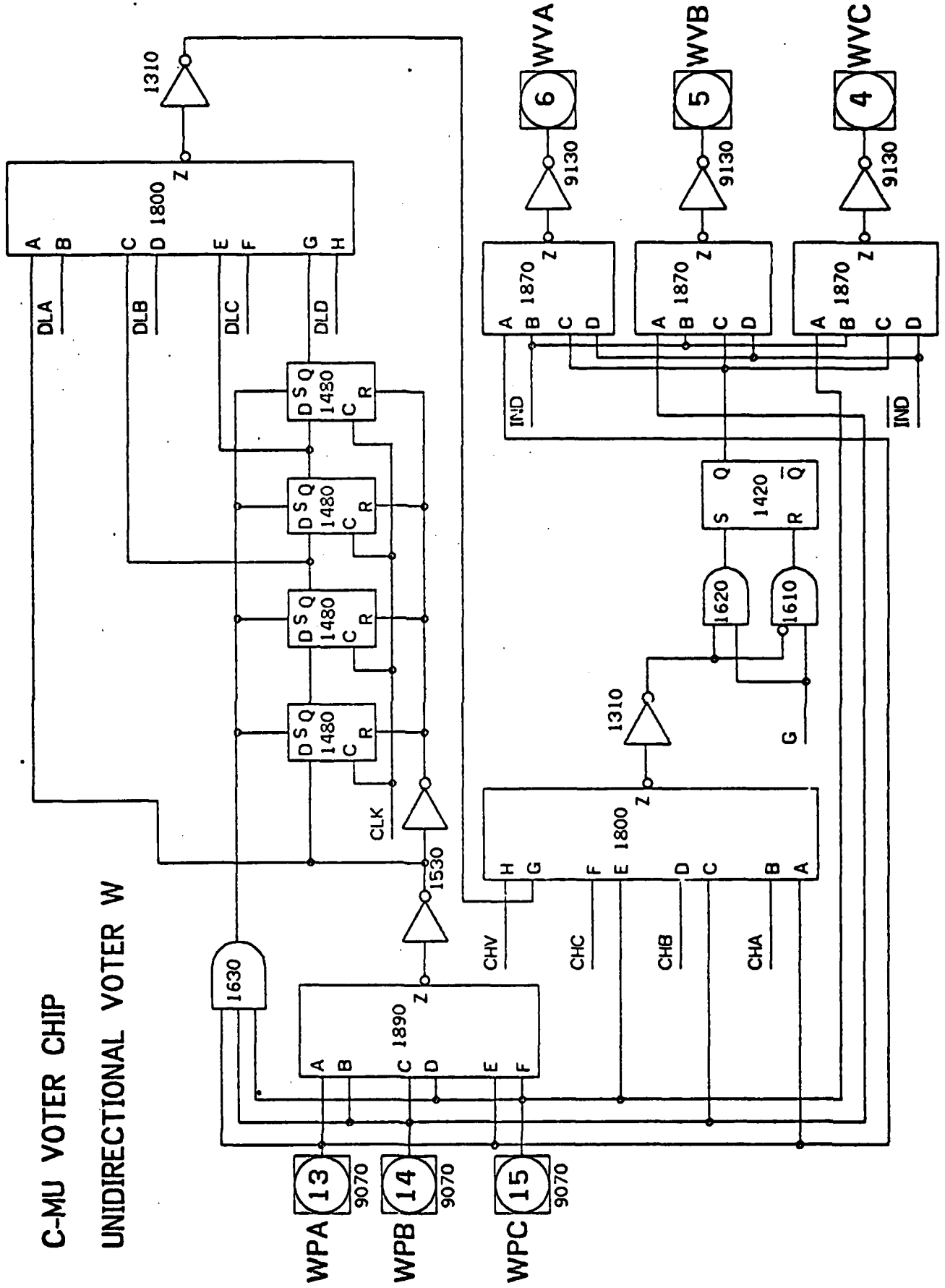
C-MU VOTER CHIP  
PIN ASSIGNMENTS

V <sub>DD</sub>	1	48	XVC
XVB	2	47	V <sub>CC</sub>
XVA	3	46	YVA
WVC	4	45	YVB
WVB	5	44	YVC
WVA	6	43	CLK
<NC>	7	42	ZEA
<NC>	8	41	ZPB
IND	9	40	ZEB
<NC>	10	39	DY
<NC>	11	38	DX
G	12	37	DIR
WPA	13	36	BY
WPB	14	35	BX
WPC	15	34	GC
XPA	16	33	GB
XPB	17	32	ZEC
XPC	18	31	ZPC
YPA	19	30	ZVC
YEA	20	29	ZVB
YPB	21	28	ZVA
YEB	22	27	ZPA
YPC	23	26	GA
YEC	24	25	GND

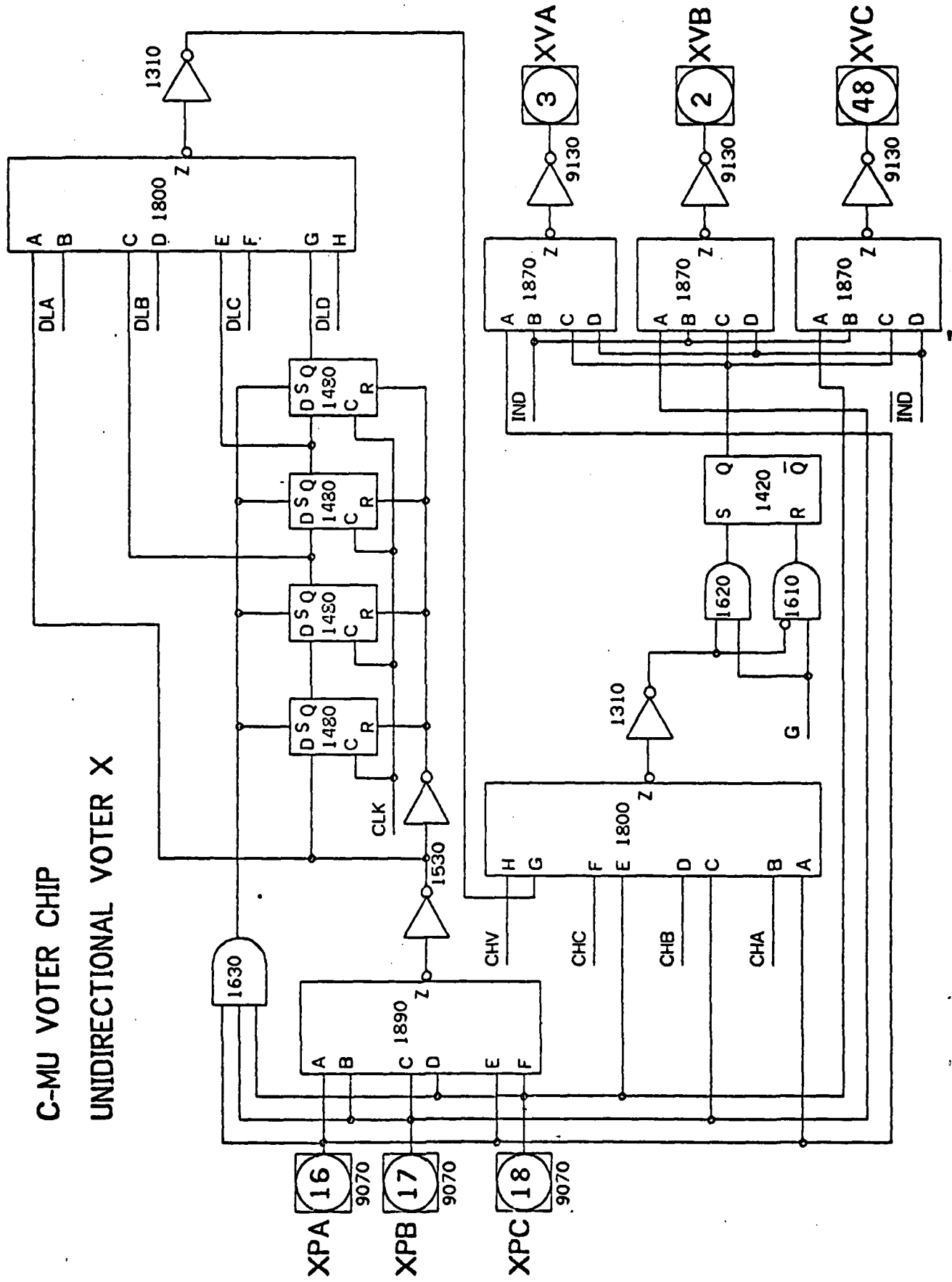
# C-MU VOTER CHIP CONTROL SECTION

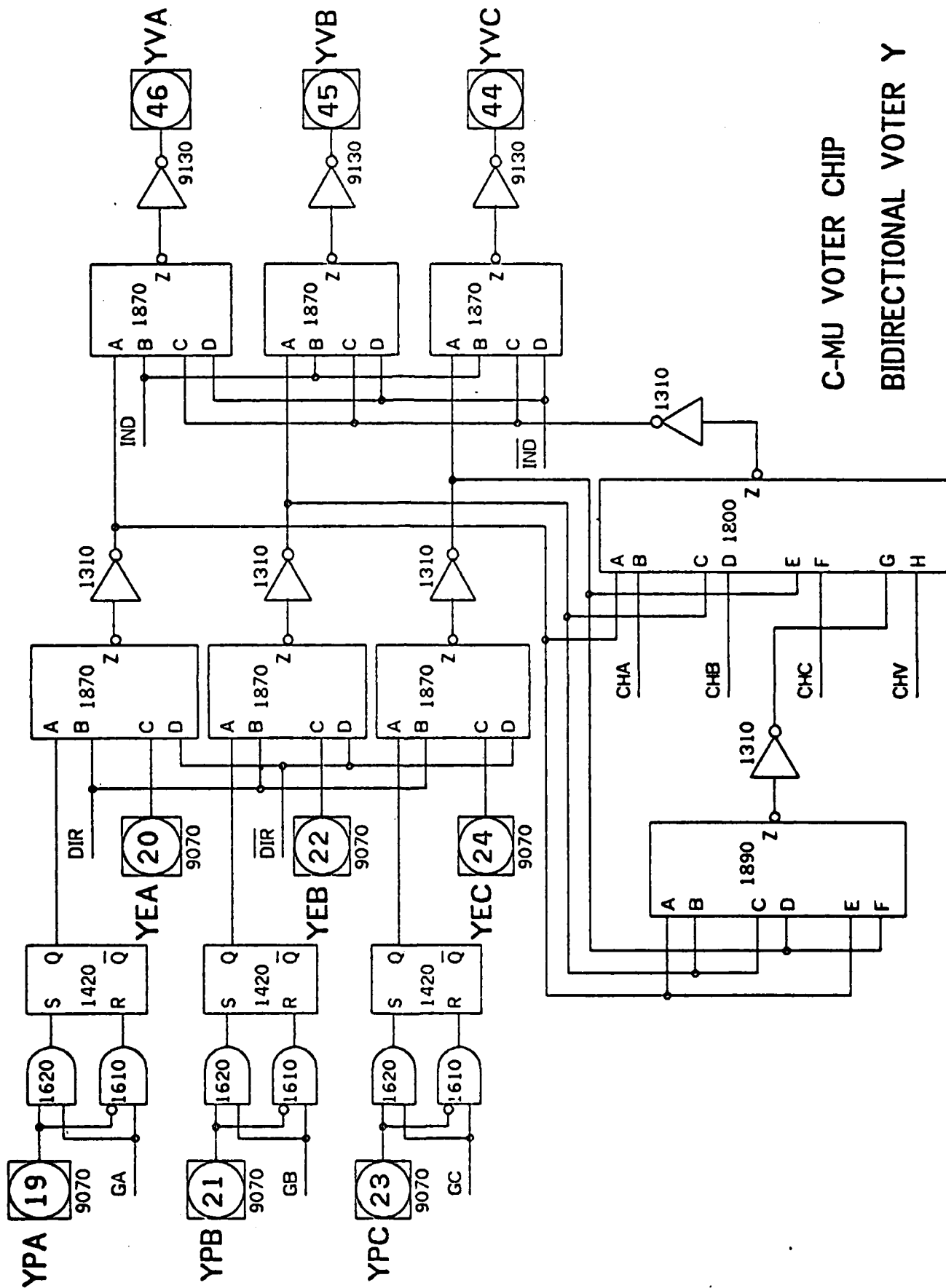


C-MU VOTER CHIP  
UNIDIRECTIONAL VOTER W



# C-MU VOTER CHIP UNIDIRECTIONAL VOTER X

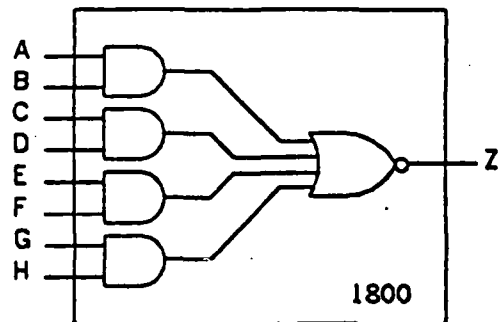
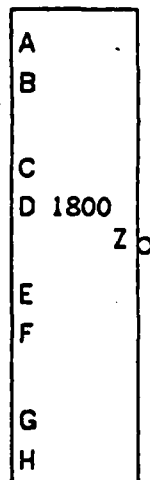
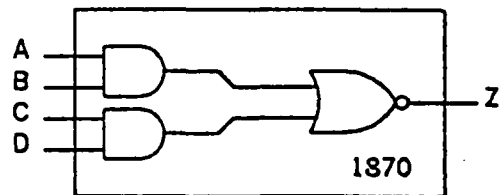
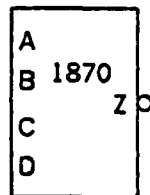
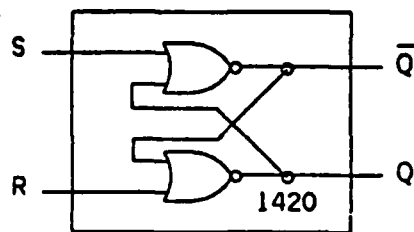
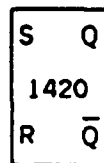
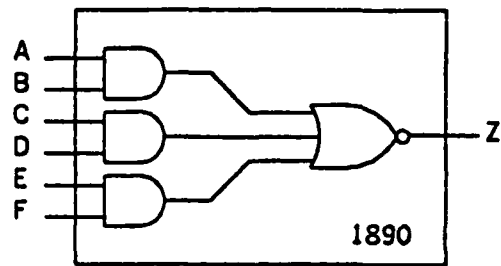
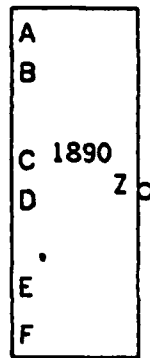




C-MU VOTER CHIP  
 BIDIRECTIONAL VOTER Y



# COMPLEX STANDARD CELLS USED IN C-MU VOTER CHIP



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